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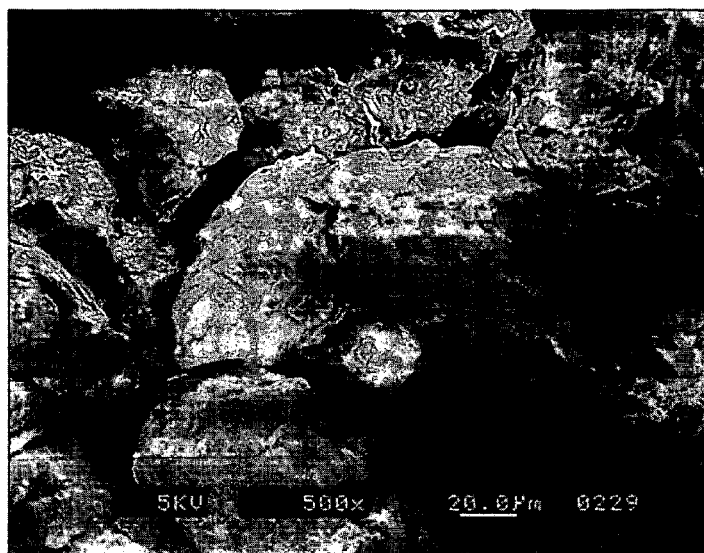
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(54) Title: THERMALLY ENHANCED ELECTRICALLY INSULATIVE ADHESIVE PASTE

**FIG. 3**



(57) Abstract: A thermal interface material comprises larger conformable thermally conductive particles, and smaller ceramic thermally conductive particles in a binder. The binder can include thermoplastic (and optionally thermoset) particles and a fugitive liquid which are substantially insoluble in each other. The binder can also include a liquid epoxy. Each of the larger thermally conductive particles is itself a cohesive yet conformable agglomeration of platy particles.

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